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(71) Applicant: SHINKAWA ELECTRIC CO., LTD.
[JP/JP]; Shinkojimachi Building 3f, 4-3-3 Kojimachi, Chiy-
oda-ku, Tokyo, 102-0083 (JP).

(72) Inventors: MATSUMOTO, Kotaro; 6-38-2-101
Machiya, Arakawa-ku, Tokyo, 116-0001 (JP). MATSU-
DA, Hiroyuki; 7-d-104 Horiguchi, Kanazawaku, Yokoya-
ma-shi, Kanagawa, 236-0054 (JP). AOKI, Hiroshi;
50-19-3-202 Nakano, Aki-ku, Hiroshima-shi, Hiroshima,
739-0321 (JP). TERADA, Masaru; 304 Sherwood Forest
Place, Cary, NC 27519 (US). EMERSON, Ovel; 803 N
Park Avenue, Dunn, NC 28334 (US). LOWE, Paul, A.;
2316 Hardwood Drive, Hillsborough, NC 27278 (US).

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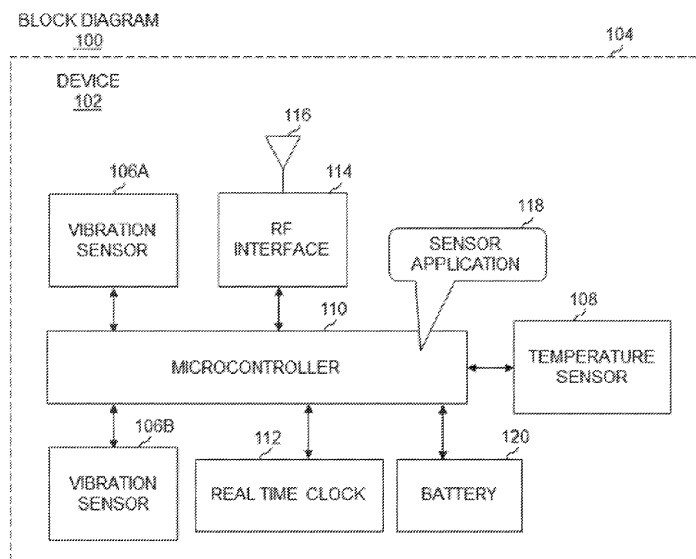


FIG. 1

(57) Abstract: Disclosed herein are devices, methods, and methods of making devices for facilitating condition monitoring of machinery allowing improve efficiencies and increased lifetime of the machinery while also reducing maintenance. In one embodiment, a device includes an enclosure assembly and a printed circuit board (PCB) assembly. The enclosure assembly includes a cap, a base mechanically coupled with the cap, and a support bracket mechanically coupled with the base. The PCB assembly includes a processor, a memory coupled with the processor, a first sensor electrically coupled with the processor, a second sensor electrically coupled with the processor, and a communication interface electrically coupled with the processor. The device, when installed, may generally form a shape of a tapered cylinder having a maximum height of 2.1 inches and a maximum diameter of 1.2 inches.

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